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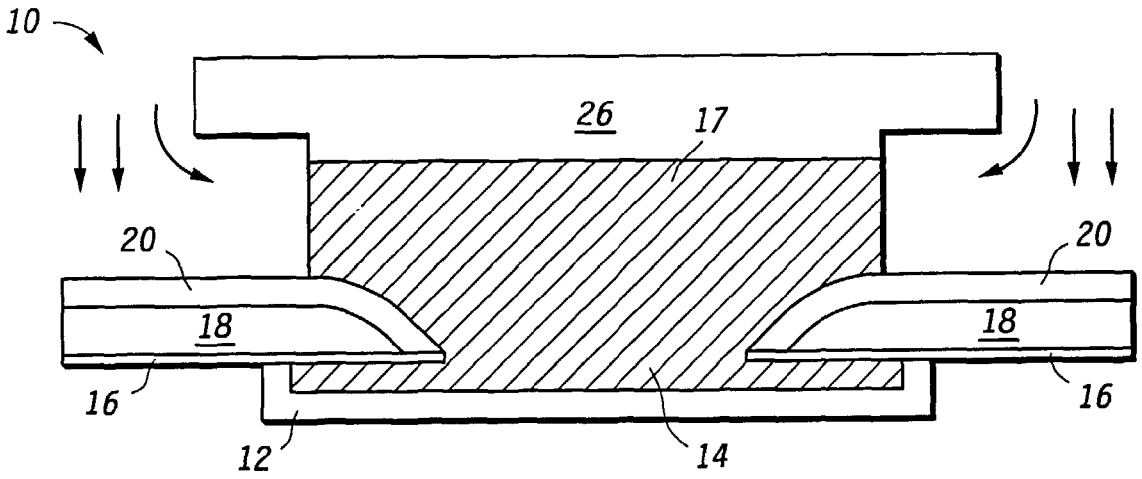
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(54) Title: METHOD AND APPARATUS FOR MANUFACTURING AN INTERCONNECT STRUCTURE



(57) Abstract: An interconnect structure (10), such as a flip-chip structure, including a base pad (14) and a stud (17) formed on the base pad (14) and extending from the base pad (14) is disclosed. The stud (17) and base pad (14) are formed to be continuous and of substantially the same electrically conductive base material. Typically, a solder structure (26) is formed on the stud (17) wherein the solder structure (26) is exposed for subsequent reflow attachment to another structure. The present invention relates to packaging integrated circuits, more particularly to the structure and processing of a stud (17) and bump without the standard under bump metallurgy.

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